

IR Reflow Profiles

Customers should consider their solder manufacturer recommended reflow profile as optimal source for their specific application. Actual temperature profile depends on various factors such as board size, board thickness, component density and solder paste etc.

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| Ramp Rate | 3°C/sec. Max. |
| Preheat | 150 to 180°C |
| | 60 to 120 sec. |
| Time Above Liquidus | 220°C |
| | 30 to 90 sec. |
| Peak Temp. | 260°C +0/-5°C |
| Time Within 5°C Peak Temp. | 10 to 20 sec. |
| Ramp Down Rate | 6°C/sec. Max. |

